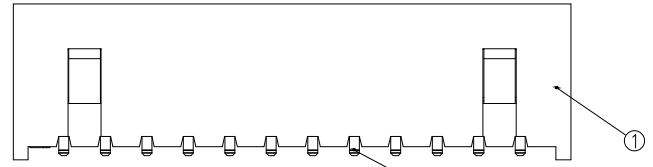
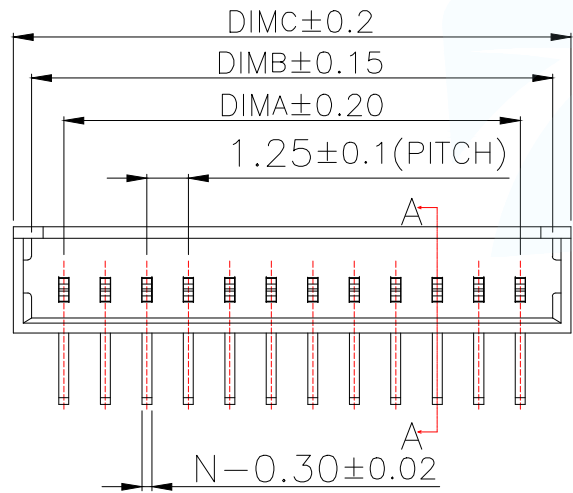
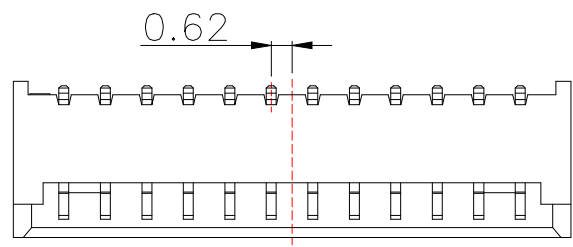


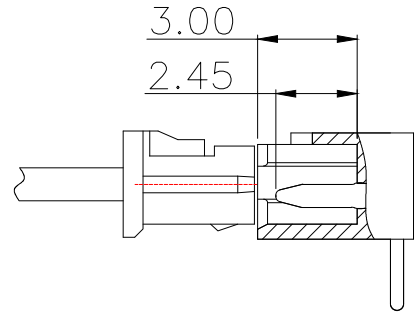
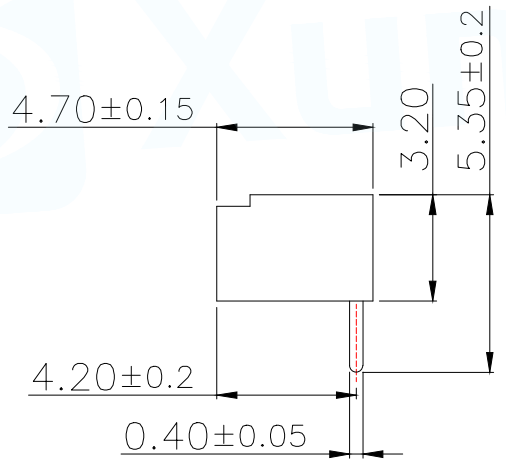
LOCK CONFIGURATION (锁扣位置)



序号	品名	材质
1	1.25 Pitch R/A Wire To Board Housing DIP(H=3.2)	PA66 UL94V-2 Red
2	1.25 Pitch R/A Wire To Board Terminal DIP(H=3.2)	Copper Alloy/Tin Plating

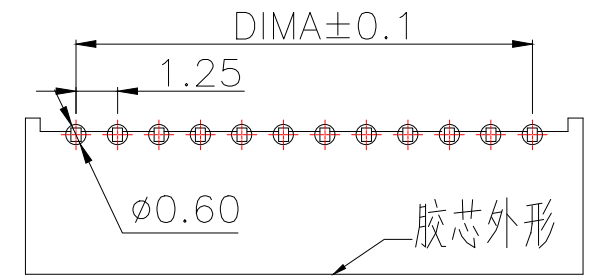
Technical Index:

- The surface of the plastic parts should be smooth, no rough edges, no obvious shrinkage, defects, cracks and other phenomena
- Lock Configuration: 2 to 3Pin is 1, ≥ 4Pin is 2
- Temperature range: -25°C~+85°C.
- Rated voltage: 125V, AC/DC.
- Contact resistance: ≤0.02Ω.
- Insulation resistance: ≥100MΩ



SECTION A-A

Part No	Pin	A	B	C
WAFER-MX1.25-2PWZ-R62	2	1.25	3.20	4.30
WAFER-MX1.25-3PWZ-R62	3	2.50	4.45	5.55
WAFER-MX1.25-4PWZ-R62	4	3.75	5.70	6.80
WAFER-MX1.25-5PWZ-R62	5	5.00	6.95	8.05
WAFER-MX1.25-6PWZ-R62	6	6.25	8.20	9.30
WAFER-MX1.25-7PWZ-R62	7	7.50	9.45	10.55
WAFER-MX1.25-8PWZ-R62	8	8.75	10.70	11.80
WAFER-MX1.25-9PWZ-R62	9	10.00	11.95	13.05
WAFER-MX1.25-10PWZ-R62	10	11.25	13.20	14.30
WAFER-MX1.25-11PWZ-R62	11	12.50	14.45	15.55
WAFER-MX1.25-12PWZ-R62	12	13.75	15.70	16.80
WAFER-MX1.25-13PWZ-R62	13	15.00	16.95	18.05
WAFER-MX1.25-14PWZ-R62	14	16.25	18.20	19.30
WAFER-MX1.25-15PWZ-R62	15	17.50	19.45	20.55
WAFER-MX1.25-16PWZ-R62	16	18.75	20.70	21.80
WAFER-MX1.25-17PWZ-R62	17	20.00	21.95	23.05
WAFER-MX1.25-18PWZ-R62	18	21.25	23.20	24.30
WAFER-MX1.25-19PWZ-R62	19	22.50	24.45	25.55
WAFER-MX1.25-20PWZ-R62	20	23.75	25.70	26.80



适用线路板(PCB LAYOUT)

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:1.25 PITCH H3.2 R/A WIRE TO BOARD DIP CONN.
DECIMALS:	ANGLES:		PAR WAFER-MX1.25-NPWZ-R62
X.:±0.50	X':.:±5°		DWN
.X.:±0.20	X.X':.:±3°		CHKD
.XX.:±0.10	X.XX':.:±1°	APVD	SCALE:1:1 UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1 REV:A